IN THE CLAIMS

Please amend and consider the claims as follows.

B1

1. (Currently Amended) An ~~windowframe capacitor~~apparatus, comprising:

a ~~housing~~unitary capacitor having a bottom surface, a top surface, and an aperture in a central portion thereof extending from the top surface to the bottom surface; and

~~capacitive material disposed within the housing to create a desired amount of capacitance;~~

wherein the bottom surface is provided with electrical connections adapted to be connected to a substrate.

2. (Currently Amended) The ~~windowframe capacitor~~apparatus of Claim 1, wherein the aperture is rectangular.

3. (Currently Amended) The ~~windowframe capacitor~~apparatus of Claim 1, wherein the ~~capacitive material~~unitary capacitor comprises a layer of an electrically conductive material and a layer of a dielectric material.

4. (Currently Amended) The ~~windowframe capacitor~~apparatus of Claim 3, wherein ~~the~~a housing of the unitary capacitor is made from a plastic material.

5. (Currently Amended) The ~~windowframe capacitor~~apparatus of Claim 1, wherein said electrical connections provided on the bottom surface comprise a ball grid

array.

6. (Currently Amended) The ~~windowframe capacitor~~apparatus of Claim 1, wherein the ~~capacitive material~~unitary capacitor ~~and the housing~~ comprises co-fired ceramic.

7. (Currently Amended) The ~~windowframe capacitor~~apparatus of Claim 1, wherein the aperture is configured to fit over a semiconductor die, and wherein said electrical connections are configured for connection to a package substrate on which the semiconductor die is mounted.

8. (Currently Amended) A semiconductor package assembly, comprising:

a semiconductor die mounted on a portion of a top surface of a package substrate; and

a unitary windowframe capacitor having an aperture formed therein, and mounted on the top surface of the package substrate surrounding the semiconductor die, wherein the unitary windowframe capacitor is arranged to substantially cover an available area of the top surface of the package substrate.

9. (Original) The semiconductor package assembly of Claim 8, further comprising an electronic component mounted on a top surface of the windowframe capacitor.

10. (Original) The semiconductor package assembly of Claim 8, further comprising a second windowframe capacitor mounted on a top surface of the first windowframe capacitor.

11. (Original) The semiconductor package assembly of Claim 8, wherein the aperture is rectangular.

12. (Original) The semiconductor package assembly of Claim 8, wherein the windowframe capacitor comprises a housing.

13. (Original) The semiconductor package assembly of Claim 12, wherein the windowframe capacitor comprises a capacitive material disposed within the housing.

14. (Original) The semiconductor package assembly of Claim 13, wherein the capacitive material comprises a layer of an electrically conductive material and a layer of a dielectric material.

15. (Original) The semiconductor package assembly of Claim 14, wherein the housing is made of a plastic material.

16. (Original) The semiconductor package assembly of Claim 13, wherein the capacitive material and the housing comprise a co-fired ceramic.

17. (Original) The semiconductor package assembly of Claim 8, wherein the windowframe capacitor is mounted on the package substrate via a ball grid array.

18. (New) The semiconductor package assembly of Claim 8, wherein the available surface area is substantially equal to an area of the top surface of the package substrate less an area of the semiconductor die.